

Choosing an Appropriate Pull-up/Pull-down Resistor for Open Drain Outputs

Ben Hopf

PMP-DC/DC Low-Power Converters

ABSTRACT

Many ICs contain digital output pins to indicate certain statuses to the rest of the system. These outputs fall into two categories: open drain (open collector for bipolar outputs) or push-pull (also known as totem pole). Open drain outputs are commonly utilized because they offer several advantages when compared to push-pull outputs. Unlike push-pull outputs, several open drain outputs from different devices can be connected directly together to create an OR function. Also, open drain outputs provide more flexibility to a designer as they can be pulled-up to any voltage found in the system, which can be useful when they serve as inputs to a processor which might require a lower voltage level than the push-pull output would give. Examples of open drain outputs commonly found on ICs include Power Good (PG) and Low Battery (LBO) on switching regulators, reset and Power Fail (PFO) on supply voltage supervisors (SVS), and Low Battery, Power Fail, and reset on power management units. All open drain outputs require the use of an external pull-up or pull-down resistor to keep the digital output in a defined logic state. This application report discusses when to use a pull-up or pull-down resistor, the factors that should be considered when selecting a pull-up or pull-down resistor, and how to calculate a valid range for the value of the resistor.

Contents

1	Introduction	2
2	Calculating the Pull-up Resistor Range	2
3	Calculating the Range of $R_{\text{Pull-up}}$ for the TPS62067	4
4	Calculating the Pull-down Resistor Range	5
5	Calculating the Range of $R_{\text{Pull-down}}$ for the TL7759	6
6	Other Selection Considerations	7
7	Conclusion	8

List of Figures

1	Typical PG Output Equivalent Circuit (PG Floating High)	2
2	Typical PG Output Equivalent Circuit (PG Low)	3
3	Reset Output Equivalent Circuit (Reset Floating Low)	5
4	Reset Output Equivalent Circuit (Reset High)	6

List of Tables

1	PG Output IC	4
2	EN Input IC	4
3	Reset Output IC	6
4	Typical Reset Input IC	7

1 Introduction

An SVS monitors a critical voltage within a system and outputs a reset signal if that voltage drops below a specified threshold. This reset signal is the open drain output in need of a pull-up or pull-down resistor. An SVS can also have an open drain PFO output that asserts if some voltage in the system drops below a specified threshold.

In a power converter, a PG output is routinely used to drive the enable input of a subsequent IC. A PG output is low if the chip's output voltage is below a certain percentage of its nominal value. The PG output is then pulled high by the external pull-up resistor when the voltage has reached the specified level. Power converters can also contain LBO outputs that are asserted if the LBI pin voltage drops below a specified threshold.

The first thing to recognize when dealing with an open drain output is whether a pull-up or a pull-down resistor is needed. This depends on whether the IC drives the output high or low when it wants to assert it. For example, the TPS62067 step-down converter has a PG output that it drives low if the chip's output voltage is not in regulation. Therefore, PG needs a *pull-up* resistor that pulls the PG pin high when the chip allows it to float, indicating that power is good. On the other hand, the TL7759 SVS has a reset output that it drives high when it detects a supply voltage drop below a specific threshold. This reset output needs a *pull-down* resistor to pull it low when that voltage is above the specified threshold.

To determine the value of the pull-up or pull-down resistor, several factors need to be taken into consideration. These include the output pin's leakage current, the leakage current of the input pin that the open drain output is connected to, the voltage that the output is being pulled up to, the high or low voltage logic level of both the output pin and the input pin that the output is connected to, and the test current used to obtain the high or low voltage logic level. This report analyzes one open drain output and one open collector output. The first example features the TPS62067 step down converter and demonstrates when a pull-up resistor is needed and how to calculate a range for it. The second example uses the TL7759 SVS and demonstrates when a pull-down resistor is needed and how to calculate a range of values for it.

2 Calculating the Pull-up Resistor Range

Figure 1 shows typical PG output circuitry. The PG output connects to the output voltage, V_{OUT} , through a pull-up resistor, $R_{PULL-UP}$, and then connects to the EN input of another chip.

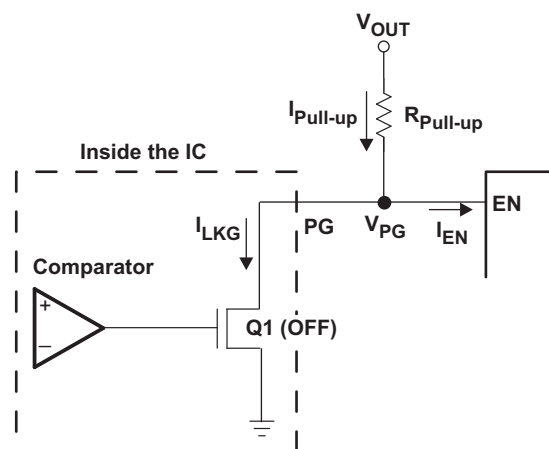


Figure 1. Typical PG Output Equivalent Circuit (PG Floating High)

The circuit in **Figure 1** is analyzed to find the maximum value for $R_{PULL-UP}$ when power is good and Q1 is off. Although Q1 is off, the datasheet specifies that there is some leakage current through it. This value is found in the datasheet as I_{LKG} , the leakage current into the PG pin. This leakage current creates a voltage drop across the pull-up resistor. Thus, the voltage on the PG pin and on the subsequent EN input is less

than V_{out} . For the calculation of the maximum value of $R_{Pull-up}$, the maximum value of I_{LKG} is used because it would result in the largest voltage drop across $R_{Pull-up}$. Also, assuming that the PG output feeds the EN input on another chip, there will also be a current flowing into that EN input. This value is found in the datasheet of the subsequent part and is labeled I_{EN} in Figure 1. Equation 1 shows how to calculate $I_{Pull-up}$ using Kirchhoff's Law.

$$I_{Pull-up} = I_{EN} + I_{LKG} \quad (1)$$

To calculate the maximum value of the pull-up resistor, Equation 2 sets the voltage at the PG pin, V_{PG} , equal to the subsequent chip's EN pin's V_{IH} . V_{IH} is the minimum voltage that is specified to be read as a logic high.

$$R_{Pull-up,max} = \frac{V_{out} - V_{IH}}{I_{Pull-up}} \quad (2)$$

This value is a maximum because choosing a larger resistor would result in a larger voltage drop across $R_{Pull-up}$ which would cause V_{PG} to be lower than the minimum value of V_{IH} . In other words, the subsequent chip would not recognize the PG voltage as being a logic high.

Figure 2 shows the same circuit as analyzed above when Q1 is on and PG is low. This indicates that the output voltage is below regulation and power is not good.

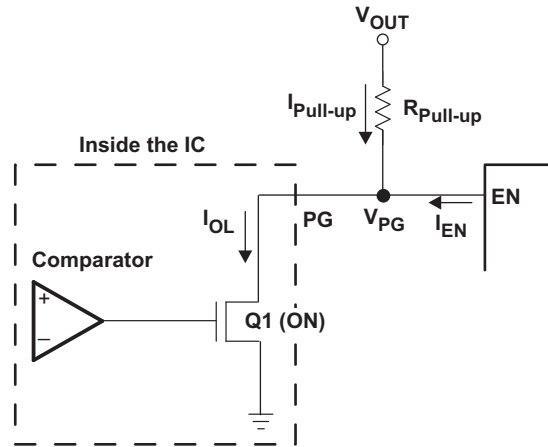


Figure 2. Typical PG Output Equivalent Circuit (PG Low)

When finding the minimum value for $R_{Pull-up}$, it is assumed that Q1 is turned on as shown in Figure 2, so V_{PG} is shorted to ground. In reality, Q1 has a resistance, $R_{DS(on)}$, which will drop some voltage and cause the PG voltage to be above ground potential. When Q1 is on, the PG voltage must be sufficiently low to register as a logic low to subsequent circuitry. To calculate the current in the pull-up resistor, the current labeled I_{OL} is needed. This value is found in the IC datasheet as the test current for V_{OL} , the output low voltage level. Setting the maximum current through Q1 equal to the current used in the test condition in the datasheet gives known performance, meaning V_{OL} will not exceed its specified maximum voltage at that current. Currents up to the specified absolute maximum PG sink current can be used, but they could yield a V_{OL} higher than its specified maximum. (In the case of the TPS62067 used in the example, its V_{OL} test current and its absolute maximum PG sink current are equal, but this is not always the case.)

Equation 3 uses Kirchhoff's Law, the IC's test current, and the leakage current of the subsequent EN input to calculate the current through the pull-up resistor.

$$I_{Pull-up} = I_{OL} - I_{EN} \quad (3)$$

The voltage across the pull-up resistor is equal to V_{out} minus V_{PG} . The datasheet gives a maximum value for V_{PG} (called V_{OL} and typically 0.3 V or 0.4 V), but it could be 0 V which would result in a higher current flowing through the pull-up resistor than if it were at the maximum specified voltage. Based on this, Equation 4 calculates the minimum pull-up resistance.

$$R_{Pull-up,min} = \frac{V_{out}}{I_{Pull-up}} \quad (4)$$

This calculation results in a minimum value because choosing any value lower for $R_{\text{Pull-up}}$ causes a higher current than the test condition current to flow in Q1. If a current higher than the test condition current flows through Q1, the voltage drop across Q1 is higher and no longer ensured. The results of Equation 4 and Equation 2 yield a range of acceptable values for the pull-up resistor $R_{\text{Pull-up}}$ at the output of the PG pin.

In the case where PG is low, the maximum allowed V_{PG} voltage depends on whether V_{OL} is greater than or less than V_{IL} , the subsequent EN pin's maximum low-level input voltage. If V_{OL} is greater than V_{IL} , then specified performance is not possible, because the maximum allowed voltage, V_{IL} , is less than the ensured highest voltage on the PG pin, V_{OL} . In this case, the minimum resistor value calculated in Equation 4 should be significantly increased to maintain plenty of margin in the PG voltage in order to achieve a sufficiently low voltage at the PG output to register as a logic low with subsequent circuitry. Since specified performance is desired, these calculations assume that V_{OL} is less than V_{IL} .

3 Calculating the Range of $R_{\text{Pull-up}}$ for the TPS62067

Table 1 gives values from the PG output IC's datasheet (in this case the TPS62067 [SLVS833A]), and Table 2 gives values for the EN input from that IC's datasheet (also a TPS62067 [SLVS833A]) that are used to calculate a range of values for the pull-up resistor at the PG output. For this example, the TPS62067's PG output drives the EN input of another TPS62067 chip.

Table 1. PG Output IC

TPS62067 DATASHEET VALUES	
PARAMETER	VALUE
IC	TPS62067
Pin	Power Good (PG)
I_{OL}	1 mA
$I_{\text{LKG(max)}}$	100 nA
$V_{\text{OL(max)}}$	0.3 V

Table 2. EN Input IC

TPS62067 DATASHEET VALUES	
PARAMETER	VALUE
IC	TPS62067
Pin	Enable (EN)
$V_{\text{IH(min)}}$	1.0 V
$I_{\text{EN(max)}}$	1000 nA
$V_{\text{IL(max)}}$	0.4 V

First, use I_{EN} , I_{LKG} , and Equation 1 to find the current through the pull-up resistor, $I_{\text{Pull-up}}$.

$$I_{\text{Pull-up}} = I_{\text{EN}} + I_{\text{LKG}} = 1000 \text{ nA} + 100 \text{ nA} = 1100 \text{ nA} \quad (5)$$

Now that $I_{\text{Pull-up}}$ has been calculated, the maximum value for $R_{\text{Pull-up}}$ is found by using Equation 2. An output voltage, V_{out} , of 1.8 V is used as an example.

$$R_{\text{Pull-up,max}} = \frac{V_{\text{out}} - V_{\text{IH}}}{I_{\text{Pull-up}}} = \frac{1.8 \text{ V} - 1.0 \text{ V}}{1100 \text{ nA}} = 727.3 \text{ k}\Omega \quad (6)$$

The next step is to find the minimum pull-up resistor value. Equation 3 is utilized to find the current through the pull-up resistor.

$$I_{\text{Pull-up}} = I_{\text{OL}} - I_{\text{EN}} = 1 \text{ mA} - 100 \text{ nA} \approx 1 \text{ mA} \quad (7)$$

With this value, Equation 4 finds the minimum value for $R_{\text{Pull-up}}$.

$$R_{\text{Pull-up,min}} = \frac{V_{\text{out}}}{I_{\text{Pull-up}}} = \frac{1.8 \text{ V}}{1 \text{ mA}} = 1.8 \text{ k}\Omega \quad (8)$$

With this final calculation, the range of pull-up resistor values is

$$1.8 \text{ k}\Omega \leq R_{\text{pull-up}} \leq 727.3 \text{ k}\Omega \quad (9)$$

4 Calculating the Pull-down Resistor Range

Figure 3 shows an IC's reset output connected to ground through a pull-down resistor, $R_{\text{Pull-down}}$. The reset pin is then connected to the reset input of a microcontroller or microprocessor.

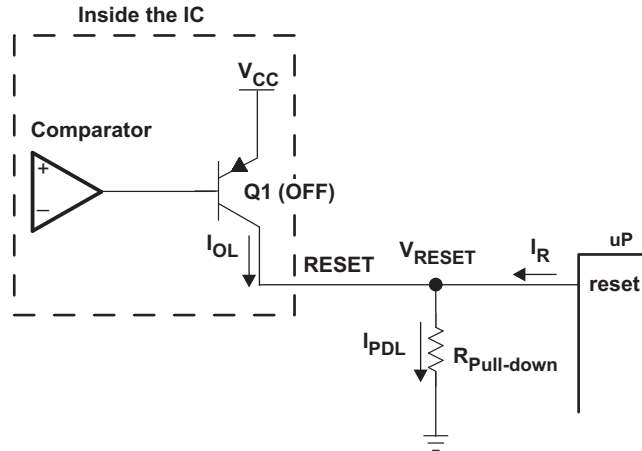


Figure 3. Reset Output Equivalent Circuit (Reset Floating Low)

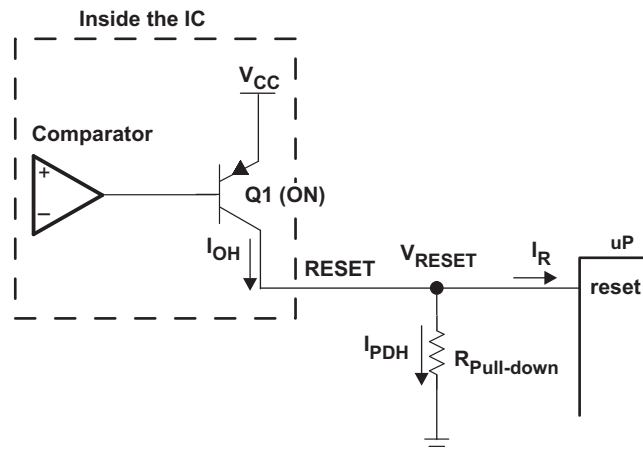
The circuit in Figure 3 is analyzed to find the maximum value for $R_{\text{Pull-down}}$, when reset is low and Q1 is off. Although Q1 is off, the datasheet specifies that there is some leakage current through it. This value is found in the datasheet as I_{OL} , the low-level output current for reset, and it creates a voltage drop across the pull-down resistor. Thus, the voltage on the reset output pin and the subsequent reset input pin is greater than zero volts. There is also current flowing out of the processor's reset input, and this value is found in the datasheet of the processor as the reset input leakage current, labeled I_{R} in Figure 3. Equation 10 uses Kirchhoff's Law to calculate the current through the pull-down resistor, I_{PDL} , when reset is pulled down.

$$I_{\text{PDL}} = I_{\text{OL}} + I_{\text{R}} \quad (10)$$

V_{IL} is found in the datasheet for the processor as the maximum low-level input voltage at its reset pin. This value represents the maximum voltage that results in the processor recognizing the reset signal as logic low. Equation 11 implements Ohm's Law to calculate the maximum value for $R_{\text{pull-down}}$.

$$R_{\text{Pull-down,max}} = \frac{V_{\text{IL}}}{I_{\text{PDL}}} \quad (11)$$

Figure 4 shows the same circuit as analyzed in Figure 3 when Q1 is on and reset is high. This indicates that the voltage being monitored by the supervisor is below the specified threshold, and the processor needs to be in reset.


Figure 4. Reset Output Equivalent Circuit (Reset High)

Using Figure 4 to find the minimum value for $R_{\text{Pull-down}}$, it is assumed that Q1 is turned on so that V_{RESET} is shorted to V_{CC} . In reality, Q1 has a saturation voltage that will cause V_{RESET} to be lower than V_{CC} . V_{RESET} must be high enough to be read as a logic high by the connected circuitry's input. The IC datasheet gives a value for the reset high-level output voltage, V_{OH} , at some test current I_{OH} . This gives known performance, meaning V_{OH} will not fall below its specified minimum. Currents up to the specified absolute maximum I_{OH} can be used, but they could yield a V_{OH} lower than its specified minimum. Equation 12 uses Kirchhoff's Law, the IC's test current, and the leakage current of the subsequent reset input to calculate the current through the pull-down resistor.

$$I_{\text{PDH}} = I_{\text{OH}} - I_{\text{R}} \quad (12)$$

After calculating the value for I_{PDH} , Equation 13 is used to find the minimum pull-down resistor value.

$$R_{\text{Pull-down,min}} = \frac{V_{\text{OH}}}{I_{\text{PDH}}} \quad (13)$$

In the case where reset is high, the minimum allowed V_{RESET} voltage depends on whether V_{OH} is greater than or less than V_{IH} , the subsequent reset input pin's minimum high-level input voltage. If V_{OH} is lower than V_{IH} , then specified performance is not possible, because the minimum required voltage, V_{IH} , is greater than the specified lowest voltage on the reset pin, V_{OH} . In this case, the minimum resistor value calculated in Equation 13 should be significantly increased to maintain plenty of margin in the reset voltage in order to achieve a sufficiently high voltage at the reset output to register as a logic high with the subsequent circuitry. Since specified performance is desired, these calculations assume that V_{OH} is greater than V_{IH} .

5 Calculating the Range of $R_{\text{Pull-down}}$ for the TL7759

Table 3 gives values from the reset output IC's datasheet (in this case the TL7759), while Table 4 gives typical values for I_{R} and V_{IL} that are found in the reset input IC's datasheet. The values from both of these tables are used to calculate a range of values for the pull-down resistor at the reset output.

Table 3. Reset Output IC

TL7759 DATASHEET VALUES	
PARAMETER	VALUE
IC	TL7759
Pin	Reset (Output)
V_{CC}	5 V
$I_{\text{OL(max)}}$	1 μA
$I_{\text{OH(min)}}$	4 V
I_{OH}	8 mA

Table 4. Typical Reset Input IC

DATASHEET VALUES	
PARAMETER	VALUE
Pin	Reset (Input)
$V_{IL(max)}$	0.3 V
$I_{R(max)}$	100 nA
$V_{IH(min)}$	3 V

First, use I_{OL} , I_R , and I_{PDL} as well as Equation 10 to find a value for I_{PDL} .

$$I_{PDL} = I_{OL} + I_R = 1 \mu A + 100 \text{ nA} = 1.1 \mu A \quad (14)$$

Now use Equation 11 to calculate the maximum value for the pull-down resistor.

$$R_{Pull-down,max} = \frac{V_{IL}}{I_{PDL}} = \frac{0.3 \text{ V}}{1.1 \mu A} = 272.7 \text{ k}\Omega \quad (15)$$

The next step is to use Equation 12 to find I_{PDH} .

$$I_{PDH} = I_{OH} - I_R = 8 \text{ mA} - 100 \text{ nA} \approx 8 \text{ mA} \quad (16)$$

Lastly, Equation 13 is utilized to find the minimum pull-down resistor value.

$$R_{Pull-down,min} = \frac{V_{OH}}{I_{PDH}} = \frac{4 \text{ V}}{8 \text{ mA}} = 500 \Omega \quad (17)$$

This final calculation yields a range for the pull-down resistor of

$$500 \Omega \leq R_{Pull-down} \leq 272.7 \text{ k}\Omega \quad (18)$$

6 Other Selection Considerations

The above examples are calculated using parameters from the datasheet that ensure performance, such as the output low voltage at a certain test current. If the current sunk by the PG pin is lower than the test condition current, then the voltage drop across the PG pin's FET is lower and the output low voltage is lower. If however, the current sunk by the PG pin is higher than the test condition current, then the voltage at the PG pin could be higher than specified, leading to an unreadable logic voltage level. Therefore, the test condition current is always used for the maximum allowed current in the above calculations because it specifies a maximum voltage at the output pin. Currents up to the absolute maximum rating of the output pin could be used, but then the output voltage at the PG or reset pin is no longer specified to fall in its specified range. To approximate the output voltage at the PG pin for currents higher than the test condition current, first the on resistance, or R_{DSon} , of the internal FET is calculated by using the specified maximum PG output-low voltage, V_{OL} , and its test current, I_{OL} .

$$R_{DSon} = \frac{V_{OL}}{I_{OL}} \quad (19)$$

Then the output voltage at the PG pin is just R_{DSon} times the new sink current.

$$V_{PG} = R_{DSon} I_{OL,new} \quad (20)$$

This voltage should remain below V_{IL} in order to be read as a logic low. Alternatively, a graph of the PG or reset voltage versus current may be shown in the datasheet. These graphs show typical performance and, like the above R_{DSon} calculation, are not specified performance measures.

After establishing the range for the pull-up or pull-down resistor, there are other factors to consider when selecting a resistor that falls within the established range. One factor that discourages using a resistor near the low end of the range is the power consumption through the pull-up or pull-down resistor and the drive circuitry. For example, if the minimum pull-down resistor of 500 Ω is used and the saturation voltage

of the BJT happens to be the maximum value of 1 V, the pull-down resistor drops $V_{CC} - 1$ V across it. If V_{CC} is 5 V, the 4 V drop across $R_{\text{Pull-down}}$ produces 8 mA of current and a resulting 32 mW power loss in the pull-down resistor plus an additional 8 mW in the IC's driver BJT. This total power loss, V_{CC} times I_{sink} , might be very significant for some applications, in which case a larger pull-down resistor should be selected.

However, there are disadvantages to selecting the largest allowed pull-up resistor. Larger resistances create a higher impedance net which is more susceptible to picking up noise from other nearby signals on the board that happen to couple to it. This is especially a concern for lengthy open drain outputs routed over a long distance.

A second concern for large resistor values is from parasitic capacitance on the open drain output. This can come from other open drain outputs OR'd together, from the downstream input pins, or from nearby traces that create a capacitor in the board. This high capacitance creates an RC circuit that has an associated rise time and fall time. Final circuit operation should be validated with these longer than normal rise and fall times.

7 Conclusion

Open drain outputs found on power devices require pull-up or pull-down resistors to keep the digital output in a defined logic state. An acceptable range of values for this resistor is calculated using circuit analysis and some parameters from the part's datasheet. Choosing an appropriate resistor value within this range ensures that the output is correctly recognized by the subsequent chip's input pin. This range of acceptable values provides flexibility in the actual value selected, which allows, for example, the reuse of a resistor value already in the Bill of Materials. The methods and equations presented in this application note can be utilized to find an appropriate range of resistor values and allows the designer to select the value that best fits the application.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Mobile Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Transportation and Automotive	www.ti.com/automotive
Video and Imaging	www.ti.com/video

TI E2E Community Home Page

e2e.ti.com

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2011, Texas Instruments Incorporated